

ABSTRACT OF THE DISCLOSURE

The invention provides a laser etching method for optical ablation working by irradiating a work article formed of an inorganic material with a laser light from
5 a laser oscillator capable of emitting in succession light pulses of a large energy density in space and time with a pulse radiation time not exceeding 1 picosecond, wherein, in laser etching of the work article formed of the inorganic material by irradiation
10 thereof with the laser light from the laser oscillator with a predetermined pattern and with a predetermined energy density, there is utilized means for preventing deposition of a work by-product around the etching position.

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